# 503314192 05/20/2015

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
JIE ZHAO	05/14/2015

# **RECEIVING PARTY DATA**

Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION
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State/Country:	CHINA
Postal Code:	201203

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14716886

## **CORRESPONDENCE DATA**

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NAME OF SUBMITTER:	MENG LIU
SIGNATURE:	/Meng Liu/
DATE SIGNED:	05/20/2015

**Total Attachments: 2** 

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PATENT 503314192 REEL: 035675 FRAME: 0315

SMIC 2014-00412-SH-US Anova Law Group, PLLC 00158.0248.00US

US Rights Page 1

ASSIGNMENT AND DECLARATION		
WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have ma		
SEMICONDUCTOR DEVICES AND FABRICATION METHOD THEREOF		
for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on(Application No); and		
WHEREAS, Semiconductor Manufacturing International (Shanghai) Corporation, a corporation of P. R. China whose post office address is 18 Zhangiiang Road, Pudong New Area, Shanghai, China 201203 (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;		
NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, provisional Application No.  Letters Patent of the United States which may be granted thereas and all		
Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all to claim priority on the basis of the above provisional application (if any), as well as all rights to claim priority on the basis of this application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof, and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign for this invention to Assignee, its successors and assigns, in accordance with the terms of this		
AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this		
AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful caths and generally do everything possible to aid Assignee, its successors and assigns, country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.		
AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No) the filing date and application number of said application when known.		

-1-

SMIC 2014-00412-SH-US Anova Law Group, PLLC 00158.0248.00US **US Rights** Page 2 Further, as a below named inventor, I hereby declare that: This declaration is directed to the application attached hereto or United States application or PCT international application number If the application is not attached hereto, the application is as identified above or by the attorney docket number as set forth above and/or the following. The above-identified application was made or authorized to be made by me. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. I have reviewed and understand the contents of the above-identified application, including the claims. I acknowledge the duty to disclose information which is material to patentability as defined in Title 37,Code of Federal Regulations § 1.56, including for continuation-in-part applications, material information which became available between the filing data of the prior application and the national or PCT International filing date of the continuation-in-part application. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. §1001 by fine or imprisonment of not more than five (5) years, or both. IN TESTIMONY WHEREOF, I/We have hereunto set our hands. Inventor Legal Name: Signature: Date: Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form or must have been previously filed. Check the box below and complete the attached page(s) to

> PATENT REEL: 035675 FRAME: 0317

Additional inventors are being named on the \_\_supplemental sheet(s) attached hereto.